

April 27, 2018

PCN

RF360 SAW components in CSSP packages for automotive electronics

As part of our efforts to further consolidate production processes and to serve the increasing demand for RF360 SAW components, 6-inch wafer material will replace 4-inch wafer material used in the front-end production processes for CSSP components for automotive electronics.

Affected products

Ordering code
B39*B26*
B39*B43* ¹⁾
B39*B44*

¹⁾excluding B39242B4346P810

For components based on 4-inch wafer material:

Deadline for last orders: March 31, 2019
Last shipments by: June 30, 2019

The announced changes will be effective for released as well as for newly designed components.

There will be no impact on product quality, specification or delivery performance. The components will be qualified according to AEC-Q200 based on reference types.

Enclosure PCN (ID No. M317)

Contact Michael Loeffler, RF360 D AE PM, Munich

Customers are asked to address inquiries directly to their sales contacts.

Product / Process Change Notification

1. ID No.: M317		2. Date of announcement: April 27, 2018	
3. Product / product group: RF360 AE CSSP components			
Old ordering code: B39*B26* B39*B43* (except B39242B4346P810) B39*B44*		New ordering code: No change	
Customer part number:			
4. Description of change: As part of our efforts to further consolidate production processes and to serve the increasing demand for RF360 SAW components, 6-inch wafer material will replace 4-inch wafer material used in the front-end production processes for CSSP components for automotive electronics.			
5. Effect on the product or for the customer (benefit / quality, specification, lead time): The changes have no effect on product quality, specifications, ordering codes or delivery performance. There is no change of packages or packing.			
6. Quality assurance measures / risk assessment: All types that change wafer size will be re-qualified according to AEC Q200 (by representative types) prior to sampling and volume production.			
7. Scheduled date of change: Deadline for last orders of components with current wafer size (LTB): March 31, 2019 Deadline for last shipments (LTS): June 30, 2019 Please note that all customers holding PPAPs and other qualification documents (mainly automotive customers) will be addressed separately by RF360 Sales.			
8. Estimated date of first delivery of changed product: April 1, 2019 If RF360 does not receive notification to the contrary within a period of 10 weeks, RF360 assumes that the customer agrees to the change. For an interim period we cannot rule out that old as well as new products will be shipped			
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Customer feedback	
Customer acknowledgement	Signature